PRODUCT / PROCESS CHANGE INFORMATION

| 1. PCI basic data | | |
|----------------------|--|--|
| 1.1 Company | | STMicroelectronics International N.V |
| 1.2 PCI No. | | ADG/22/13500 |
| 1.3 Title of PCI | | Test pattern relocation from inner dice to scribing line |
| 1.4 Product Category | | SiC |
| 1.5 Issue date | | 2022-06-15 |

| 2. PCI Team | |
|---------------------------|---------------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | ROBERTSON HEATHER |
| 2.1.2 Phone | +1 8475853058 |
| 2.1.3 Email | heather.robertson@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Maurizio Maria FERRARA |
| 2.1.2 Marketing Manager | Michele MACAUDA, Marcello SGROI |
| 2.1.3 Quality Manager | Vincenzo MILITANO |

| 3. Change | | |
|---------------------|--|----------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Wafer Fab (Process) | Mask Frame : introduction of new structure or never tested structure, change of die scribe separation or scribe line width | Shenzhen |

| 4. Description of change | | |
|---|--|---|
| | Old | New |
| 4.1 Description | For each litho mask step a die is sacrified for test pattern structure | Moving the test pattern structures to the scribe line will increase the wafer gross |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | no impact | |

| 5. Reason / motivation for change | |
|-----------------------------------|--------------------------------------|
| 5.1 Motivation | To grant a better service continuity |
| 5.2 Customer Benefit | SERVICE IMPROVEMENT |

| 6. Marking of parts / traceability of change | |
|--|-----------|
| 6.1 Description | by new FG |

| 7. Timing / schedule | |
|-------------------------------------|--------------|
| 7.1 Date of qualification results | 2022-06-09 |
| 7.2 Intended start of delivery | 2022-06-30 |
| 7.3 Qualification sample available? | Upon Request |

| 8. Qualification / Validation | | | |
|---|--|---------------|--|
| 8.1 Description | | | |
| 8.2 Qualification report and qualification results | | Issue Date | |

9. Attachments (additional documentations)

13500 Public product.pdf 13500 PCI TEG GEN1 and GEN2.pdf

| 10. Affected parts | | | |
|-------------------------|-------------------------|--------------------------|--|
| 10. 1 Current | | 10.2 New (if applicable) | |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No | |
| | SCT1000N170 | | |
| | SCT10N120 | | |
| | SCT10N120AG | | |
| | SCT20N120 | | |
| | SCT20N120AG | | |
| | SCT20N120H | | |
| | SCT30N120 | | |
| | SCT30N120H | | |
| | SCT50N120 | | |
| | SCTH100N65G2-7AG | | |
| | SCTH35N65G2V-7 | | |
| | SCTH35N65G2V-7AG | | |
| | SCTH40N120G2V-7 | | |
| | SCTH40N120G2V7AG | | |
| | SCTH70N120G2V-7 | | |
| | SCTH90N65G2V-7 | | |
| | SCTW100N65G2AG | | |
| | SCTW35N65G2V | | |
| | SCTW35N65G2VAG | | |
| | SCTW40N120G2V | | |
| | SCTW40N120G2VAG | | |
| | SCTW70N120G2V | | |
| | SCTW90N65G2V | | |



Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : Test pattern relocation from inner dice to scribing line

PCI Reference : ADG/22/13500

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

| SCTW40N120G2VAG | SCTW100N120G2AG | SCTW40N120G2V |
|------------------|------------------|------------------|
| SCTW60N120G2 | SCT10N120 | SCT10N120AG |
| SCT30N120 | SCT20N170AG | SCT50N120 |
| SCTH70N120G2V-7 | SCTH35N65G2V-7 | SCTH60N120G2-7AG |
| SCTW60N120G2AG | SCTW35N65G2VAG | SCTH100N65G2-7AG |
| SCT1000N170 | SCTW90N65G2V | SCT20N120H |
| SCTW35N65G2V | SCTH35N65G2V-7AG | SCT20N170 |
| SCT30N120H | SCT20N120 | SCT20N120AG |
| SCTH40N120G2V-7 | SCTH90N65G2V-7 | SCTW70N120G2V |
| SCTH40N120G2V7AG | SCT1000N170AG | SCTH60N120G2-7 |
| SCTW100N65G2AG | | |

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